



## CUSTOMER ADVISORY

### Package Outline Drawing Update for Trion® FPGAs

<b>Advisory Details</b>	<p>Package Outline Drawing (POD) for the affected Trion® FPGAs have been updated to reflect the correct package thickness of the FPGAs.</p> <p>There is no impact to the form, fit and function of the FPGAs as the FPGAs have been manufactured using the updated PODs at outsourced manufacturing sites since Year 2020. This update is merely for documentation correction.</p> <table><tr><th rowspan="2">Device</th><th colspan="2">Package Thickness (mm)</th></tr><tr><th>Existing POD</th><th>Updated POD</th></tr><tr><td>T4/T8 FBGA49</td><td>0.86 +/- 0.10</td><td>0.85 +/- 0.10</td></tr><tr><td>T120/T85/T55 FCCSP324</td><td>0.97 (max)</td><td>1.07 (max)</td></tr><tr><td>T120/T85/T55 FCCSP576</td><td>1.10 (max)</td><td>1.20 (max)</td></tr></table> <p>Customers can refer to the following collateral with the updated package outline drawings:</p> <ul style="list-style-type: none"><li>• <a href="#">Trion Packaging Guideline</a></li></ul>	Device	Package Thickness (mm)		Existing POD	Updated POD	T4/T8 FBGA49	0.86 +/- 0.10	0.85 +/- 0.10	T120/T85/T55 FCCSP324	0.97 (max)	1.07 (max)	T120/T85/T55 FCCSP576	1.10 (max)	1.20 (max)
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<b>Parts Affected</b>	<p>Trion® FPGAs shown below:</p> <ul style="list-style-type: none"><li>• T4F49XX</li><li>• T8F49XX</li><li>• T55F324XX</li><li>• T85F324XX</li><li>• T120F324XX</li><li>• T55F576XX</li><li>• T85F576XX</li><li>• T120F576XX</li></ul> <p>XX = All speed grades</p>														
<b>Contact:</b>	<p>For more information, please contact your local Sales or FAE or contact us online at <a href="https://www.efinixinc.com/company-contact-us.html">https://www.efinixinc.com/company-contact-us.html</a>.</p>														